

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HAMID ESLAMPOUR	03/08/2021
KARTHIK KATINGARI	03/09/2021
ADAM MARTIN	03/08/2021
RECEIVING PARTY DATA	
Name:	INVENSENSE, INC.
Street Address:	1745 TECHNOLOGY DRIVE
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95110
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17202070
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NAME OF SUBMITTER:	MARIA S. SWIATEK
SIGNATURE:	/Maria S. Swiatek/
DATE SIGNED:	03/15/2021
Total Attachments: 6	
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ASSIGNMENT

WHEREAS, the undersigned, **Hamid Eslampour**, a resident of San Jose, CA; **Karthik Katingari**, a resident of San Jose, CA; and **Adam Martin**, a resident of San Jose, CA, (collectively hereinafter termed "Inventors"), have jointly invented certain new and useful improvements in *Semiconductor Package With Built-In Vibration Isolation, Thermal Stability, And Connector Decoupling* for which invention we have executed a United States Patent Application having Serial Number 17/202,070, and Filing date March 15, 2021 and which invention is fully described in the specification pertaining to said application.

WHEREAS, **InvenSense, Inc.** (hereinafter termed "Assignee"), a body having corporate powers under the laws in Delaware, having a place of business at 1745 Technology Drive, San Jose, CA 95110, is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest (a) in and to said application and said invention, and any later filed United States utility or foreign applications claiming priority to said application; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a priority application, utility, division, substitution, or continuation of any of said

applications; and (d) in and to each and every reissue or extension of any of said patents; and (e) all claims for damages by reason of past infringement of said patents together with any back damages and royalties accrued, with the right to sue for and collect the same for its own use and enjoyment, and for use and enjoyment of its successors, assigns or other legal representatives.

2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting utility, substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference, derivation or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefore and any patents granted thereon, including without limitation opposition proceedings, inter partes and ex parte re-examination proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.

3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor, his respective heirs, legal representatives and assigns.

4. Said Inventors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. The undersigned hereby grant(s) the firm of DLA Piper LLP (US), 2000 University Avenue, East Palo Alto, CA 94303 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document in connection with U.S. Patent Application entitled: ***Semiconductor Package With Built-In Vibration Isolation, Thermal Stability, And Connector Decoupling***


(Hamid Eslampour) (Mar 8, 2021 20:18 PST)

Mar 8, 2021

Hamid Eslampour

Date

Karthik Katingari

Date

Adam Martin

Date

ASSIGNMENT

WHEREAS, the undersigned, **Hamid Eslampour**, a resident of San Jose, CA; **Karthik Katingari**, a resident of San Jose, CA; and **Adam Martin**, a resident of San Jose, CA, (collectively hereinafter termed "Inventors"), have jointly invented certain new and useful improvements in *Semiconductor Package With Built-In Vibration Isolation, Thermal Stability, And Connector Decoupling* for which invention we have executed a United States Patent Application having Serial Number 17/202,070, and Filing date March 15, 2021 and which invention is fully described in the specification pertaining to said application.

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applications; and (d) in and to each and every reissue or extension of any of said patents; and (e) all claims for damages by reason of past infringement of said patents together with any back damages and royalties accrued, with the right to sue for and collect the same for its own use and enjoyment, and for use and enjoyment of its successors, assigns or other legal representatives.

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Hamid Eslampour

Date

/Karthik katingari/
(Karthik katingari) (Mar 8, 2021 15:09 PST)

Karthik Katingari

Mar 9, 2021

Date

/Adam martin/
(Adam martin) (Mar 8, 2021 20:17 PST)

Adam Martin

Mar 8, 2021

Date